Amendments to the Specification

Paragraph [0035] on page 11 is to be replaced with the following paragraph:

-- After the FORM CONDUCTIVE TRACES step 52, the sequence 50 proceeds to a FORM RESISTOR step 64, wherein resistive material is deposited on the planarized surface to form the resistive layer 18 thereon as shown in Figure 4E. The resistive layer 18 ~~114~~ is patterned and etched to expose a part of the first conductive trace 22 thereunder as shown in Figure 4F. Specifically, a photoresist material 56 is deposited over the resistive layer 18, masked using a second mask, exposed and developed to a second pattern on the second mask, using the photolithographic process as described above. The resistive layer 18 and photoresist material 56 are then etched using either dry or wet etch to leave the structure as shown in Figure 4F. The photoresist material 56 deposited over the resistive layer 18 is then removed before the deposition of a next layer on the structure. The photoresist material initially covers the entire top surface of the resistive layer 18. The pattern on the second mask is a pattern that defines the top surface of the resistive layer 18 that is to remain for straddling the first and second conductive traces 22, 24 after etching. During etching, the area of the resistive layer 18 that is not covered with the photoresist material 56 is etched away. --

Paragraph [0041] on page 13 is to be replaced with the following paragraph:

-- A heating element 80 (Figure 6E) according to a second embodiment of the invention is next described with the aid of Figures 5 and 6A-6D. Figure 5 is a flow chart showing a sequence 82 of steps for fabricating the heating element 80. The sequence 82 starts in a FORM CONDUCTIVE LAYER sub-step 84 of a FORM CONDUCTIVE LAYER step 52, wherein a conductive layer 20 is formed over a capping layer 12 on a substrate 10 as shown in Figure 6A. Next, a portion

of the conductive layer 20 is removed using a photolithographic process as described above to obtain the structure shown in Figure 6B. As can be seen in Figure 6B, the conductive layer 20 is separated into a first conductive trace 22 and a second conductive trace 24. The first and second conductive traces 22, 24 are separated by a void 86 therebetween to be electrically insulated from each other. --